



US00D485563S

(12) **United States Design Patent**  
**Wei**

(10) **Patent No.:** **US D485,563 S**

(45) **Date of Patent:** **\*\* Jan. 20, 2004**

(54) **ELECTRONIC DEVICE ENCLOSURE**

(75) **Inventor:** **Tzu-Hao Wei**, Hacienda Heights, CA  
(US)

(73) **Assignee:** **Hon Hai Precision Ind. Co., Ltd.**,  
Taipei Hsien (TW)

(\*\*) **Term:** **14 Years**

(21) **Appl. No.:** **29/164,073**

(22) **Filed:** **Jul. 15, 2002**

(51) **LOC (7) Cl.** ..... **14-03**

(52) **U.S. Cl.** ..... **D14/496**

(58) **Field of Search** ..... D14/496, 133,  
D14/135, 435, 454, 483; D21/324, 332;  
273/148 B; 463/30-47; 206/308.1, 308.3,  
307; 345/905

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

- D264,969 S \* 6/1982 McGourty ..... D14/496
- D297,007 S \* 8/1988 Pushelberg ..... D14/496
- 4,976,435 A \* 12/1990 Shatford et al. .... 345/156

- 5,192,082 A \* 3/1993 Inoue et al. .... 463/44
- D395,652 S \* 6/1998 Grimm et al. .... D14/496
- 5,865,677 A \* 2/1999 Goldfarb et al. .... 463/46
- D469,109 S \* 1/2003 Andre et al. .... D14/496
- D472,245 S \* 3/2003 Ander et al. .... D14/496
- 6,540,611 B1 \* 4/2003 Nagata ..... 463/46

\* cited by examiner

*Primary Examiner*—Prabhakar Deshmukh

(74) *Attorney, Agent, or Firm*—Wei Te Chung

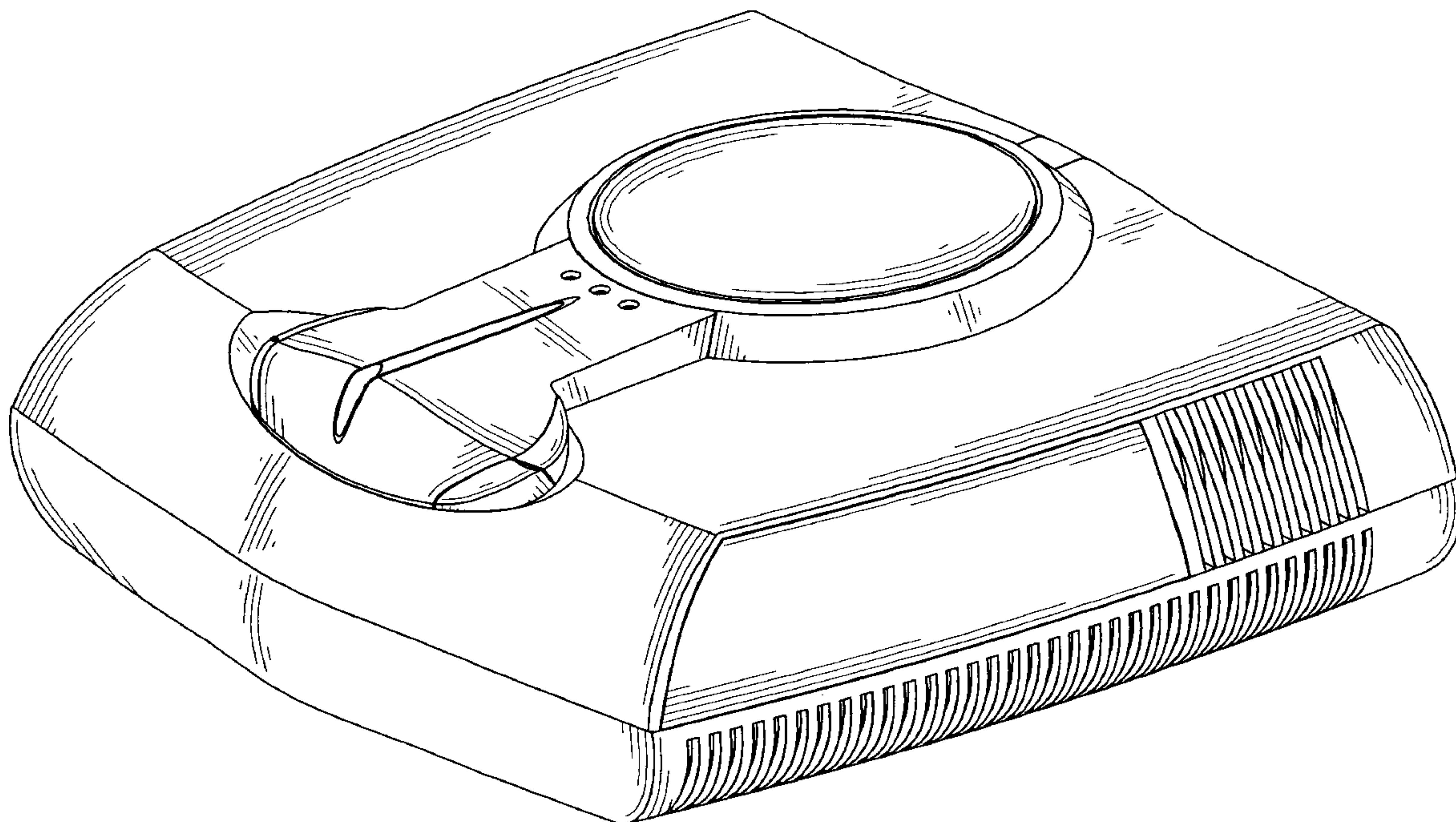
(57) **CLAIM**

The ornamental design for an electronic device enclosure, as shown.

**DESCRIPTION**

FIG. 1 is a perspective view of an electronic device enclosure of my new design;  
 FIG. 2 is a front elevational view thereof;  
 FIG. 3 is a rear elevational view thereof;  
 FIG. 4 is a left side elevational view thereof;  
 FIG. 5 is a right side elevational view thereof;  
 FIG. 6 is a top plan view thereof; and,  
 FIG. 7 is a bottom plan view thereof.

**1 Claim, 5 Drawing Sheets**



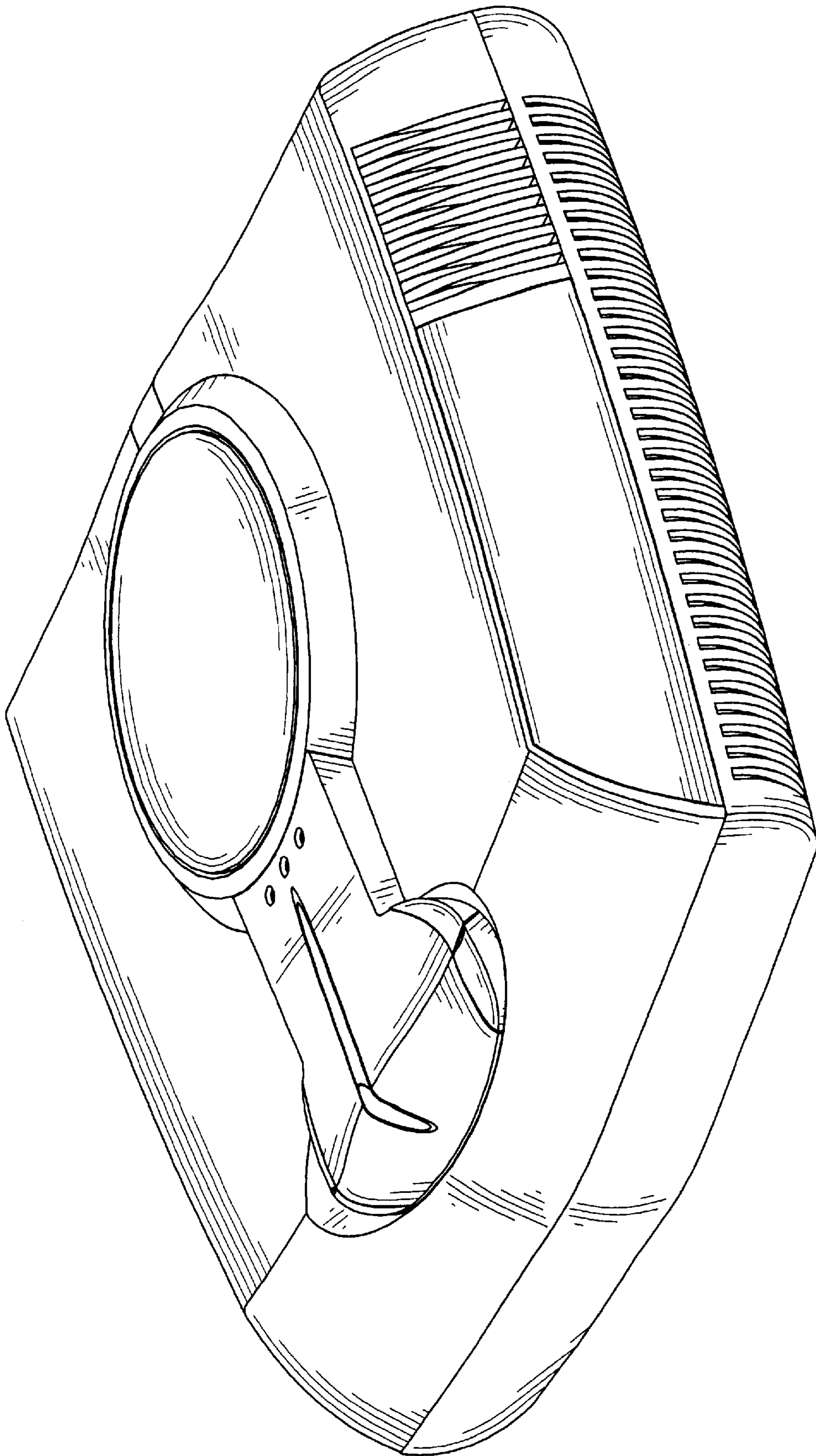


FIG. 1

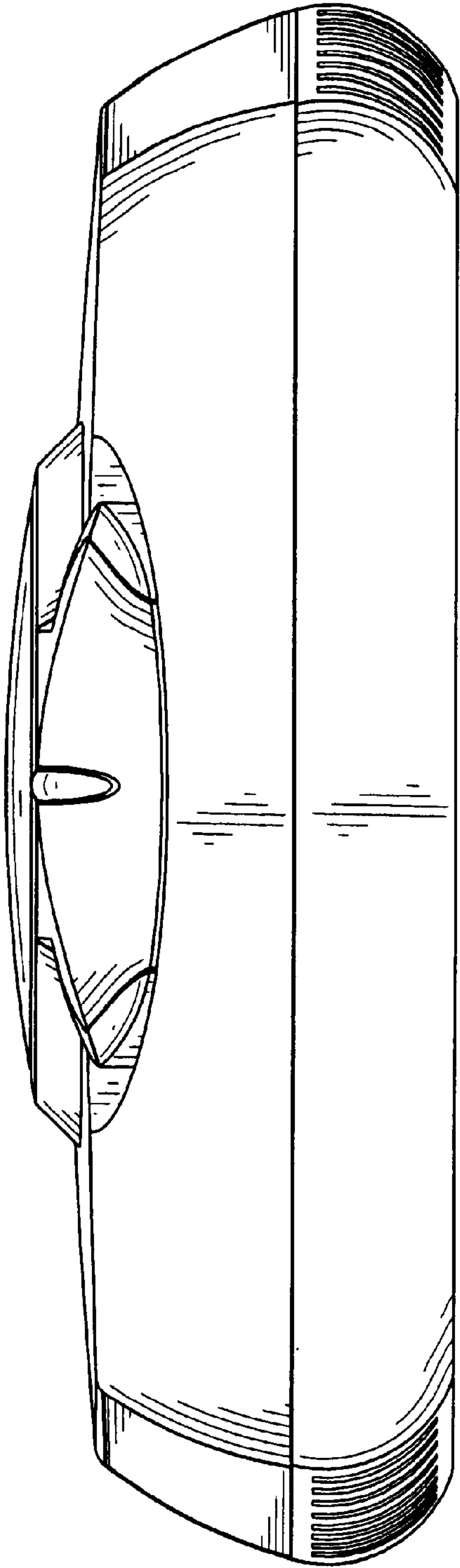


FIG. 2

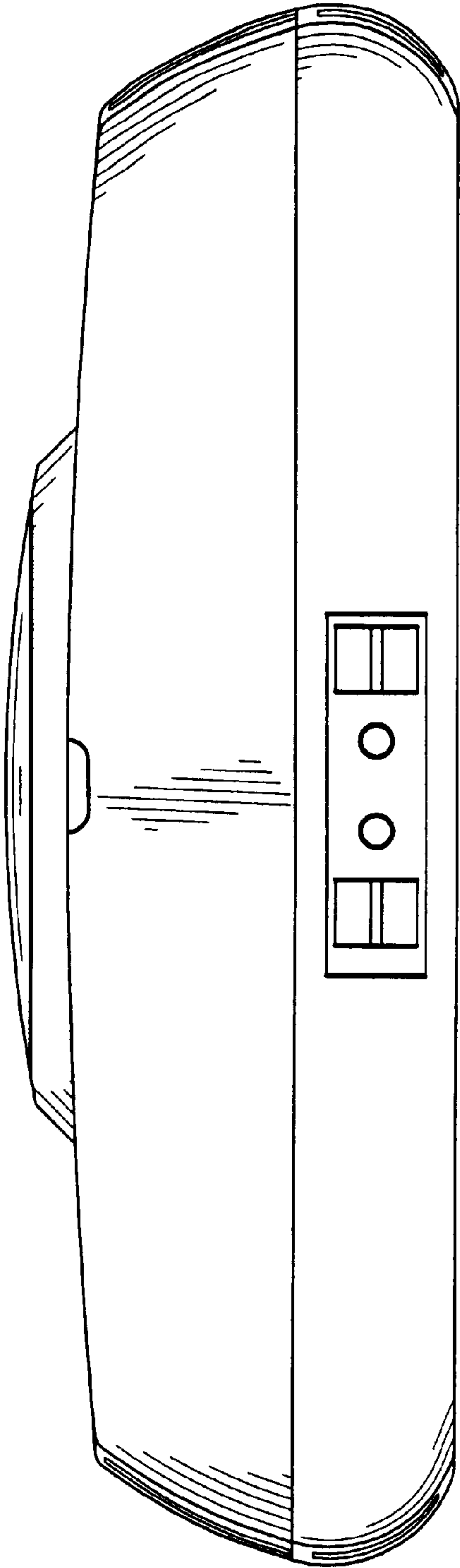


FIG. 3

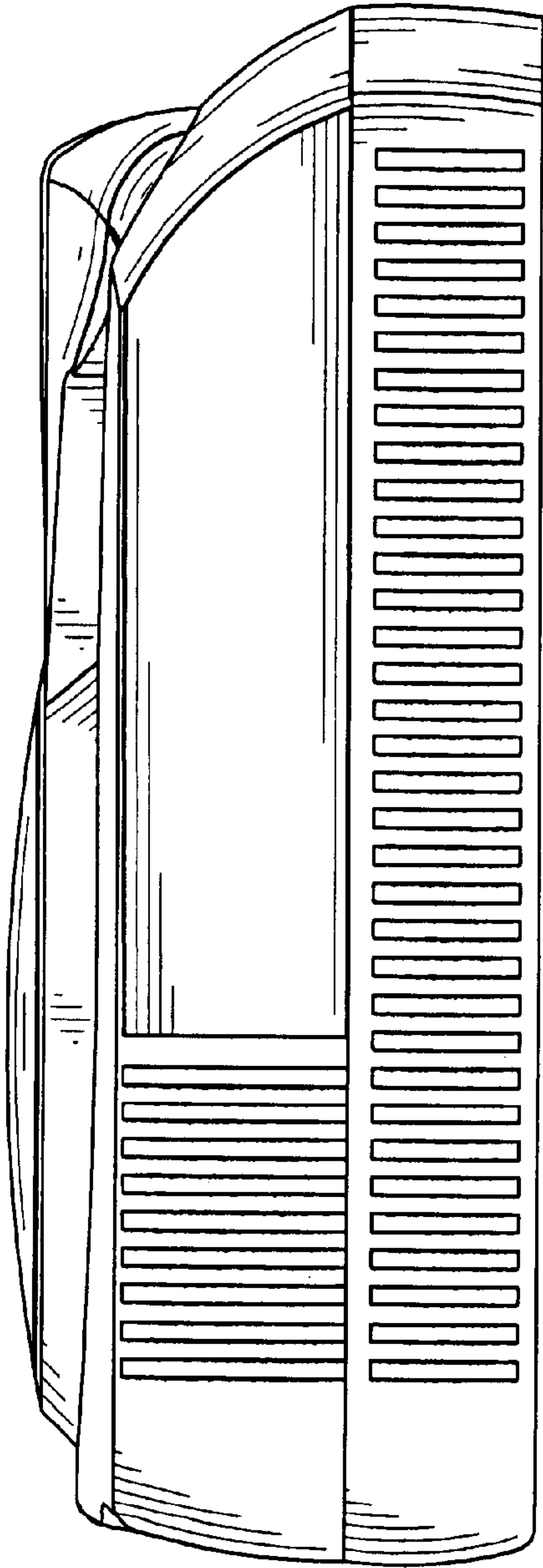


FIG. 4

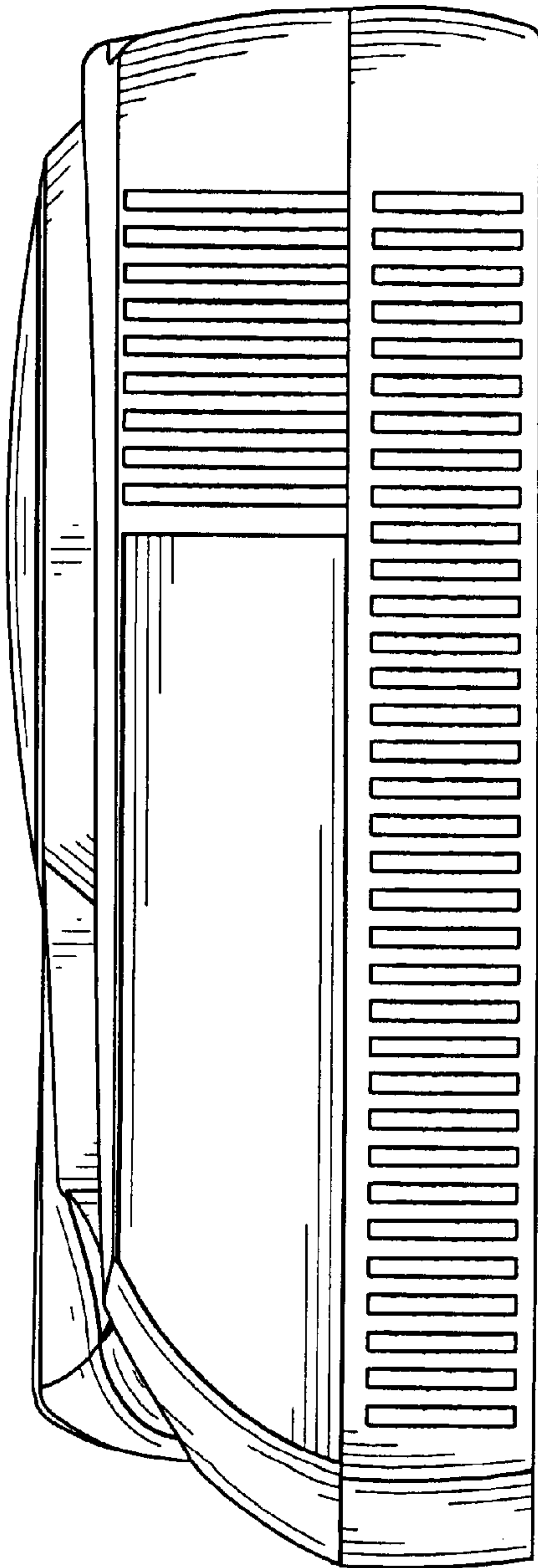


FIG. 5



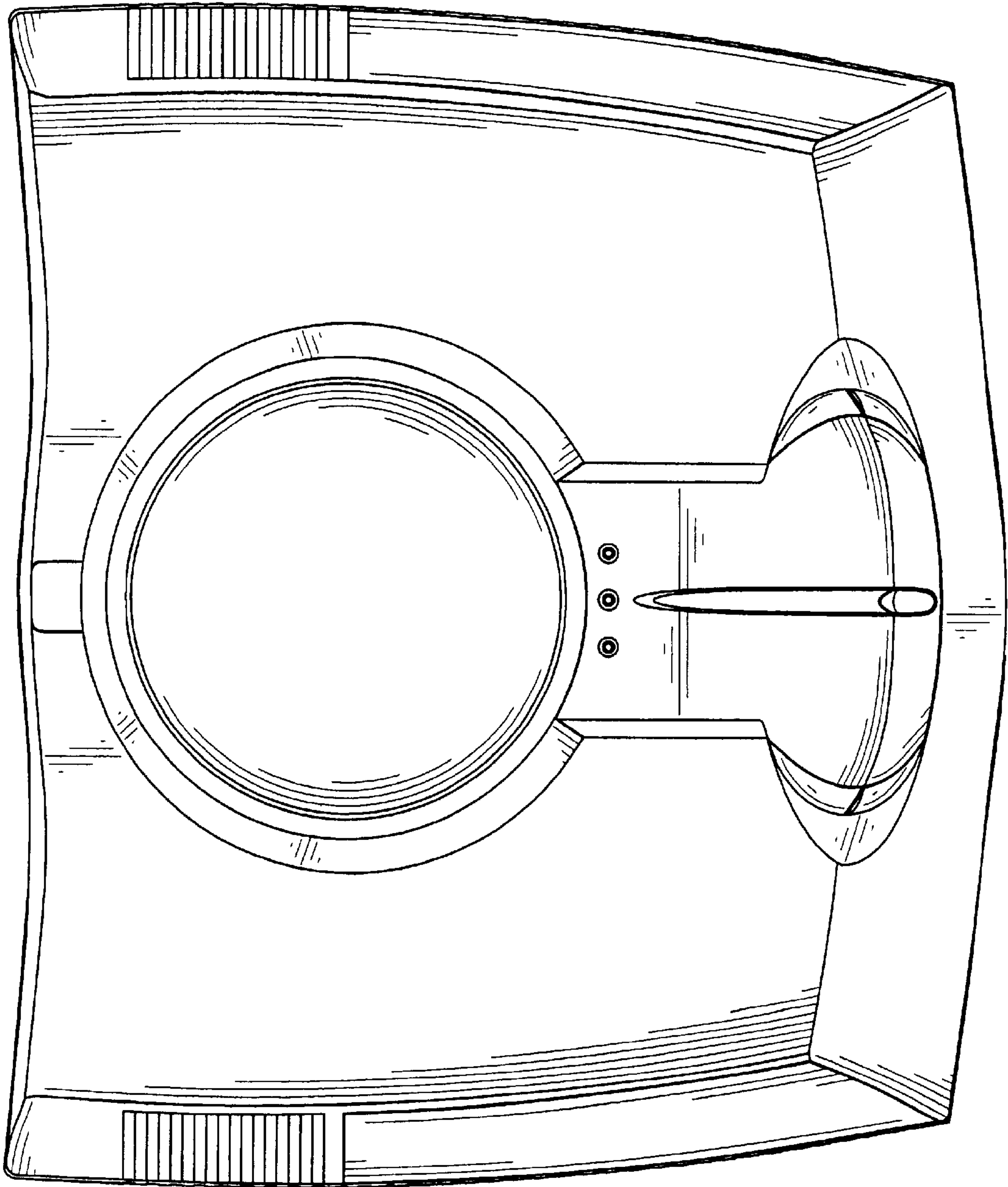


FIG. 6

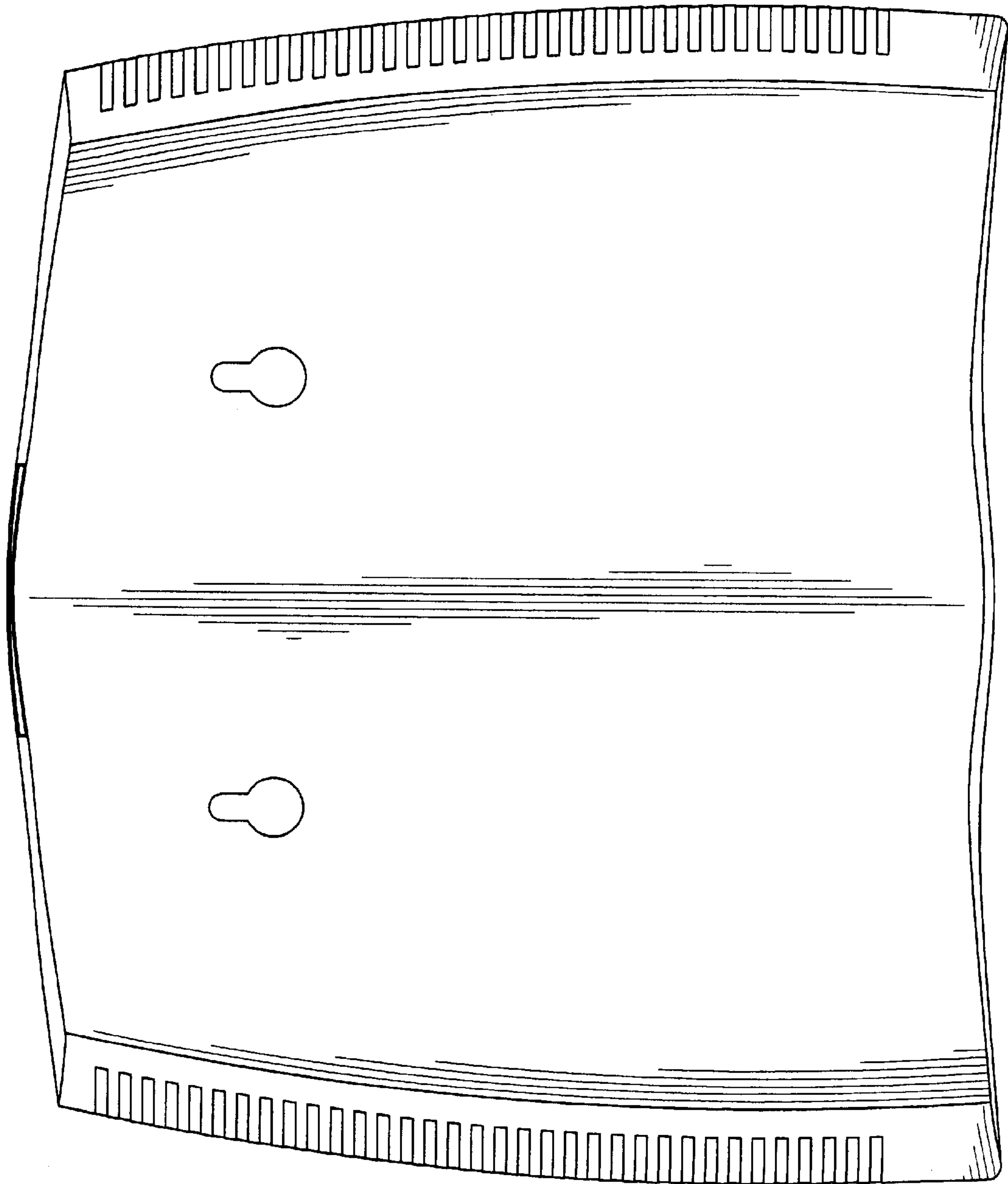


FIG. 7